

A MECHANISM TO REDUCE WASTE DUE TO VOLTAGE DIPS IN NARROW FABRIC LOOMS

A dissertation submitted to the Department of Electrical Engineering, University of Moratuwa in partial fulfillment of the requirements for the Degree of Master of Science

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Abstract

Like any other industry, apparel industry too tries to minimize their product cost by reducing production waste. Voltage fluctuations and power failures are two of the most concerning factors affecting the production. Even though these voltage fluctuations & voltage failures affect different kinds of looms at different degrees, its effect on the weaving looms which manufacture elastics is severe. As a narrow fabric elastic manufacturer it has been faced difficulties in minimizing the number of joints in the fabric (tape), which is a direct consequence of the same.

There are no research papers or commercial devices found to minimize the fabric joints in case of voltage dips or short period voltage interruptions. The significance of the proposed system is its ability to sense the voltage dips/sags or interruption with the fast AC to DC converter and take decisions intelligently to suit the situation prevailed, e.g. whether to let the machine run or stop depending on the time elapsed.

The brain of the controller 0" isa '--peripheral interface controller (PIC) and is programmed as assembly language. MPLAB Software compiles assembly to hex codes and the required sequence of signals is generated from PIC. This signal is sent to control unit of the loom via the DPDT relay to hold down the control. switches to perform the controller operations of the looms within a 3 second period during the short-time voltage variations such as interruptions and dips.

Numerous other applications are possible with this system in other industries too. One is in the rubber extruder and another is mixing mill in manufacturing rubber tires.

DECLARATION

The work submitted in this dissertation is the result of my own investigation, except where otherwise stated.

It has not already been accepted for any degree, and is also not being concurrently submitted for any other degree.

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Chapter 1

Introduction

1.1 Background

Apparel industry requires to provide efficient and on time service to the customers with no compromise on the quality of goods being delivered. One major determinant of the quality of the narrow fabric elastics is the number of joints of one tape per unit length which is predetermined.

The textile industry is an amalgam of related industries which uses variety of natural & synthetic materials. Among the machines which are used in apparel industry the machine type that it has been chosen to carry out my project is a narrow fabric weaving loom. However this can be implemented to other machinery in different industries with small changes.

Current loom capacity in the factory is 120 (100nos of single deck and 20 nos of double deck). Each single deck loom can be produced 10 tapes and 20 by double deck looms which leads to an average daily production of 0.4 million meters.

Narrow fabric manufacturers face difficulties in reducing the number of joints in the continuous fabric tapes. Since there is a particular number of joints that the narrow fabric can have which is of course pre-specified by the customer, any instance which exceeds the same will lead to heighten the factory production waste since it will not be accepted by the customer. The study helped in identifying following reasons as the causes of waste generation.

- 1. Voltage variation
- 2. power interruption
- 3. Machine break downs
- 4. Quality problems
- 5. Yarn breakages
- 6. Generator change over & vice versa
- 7. Process problems and many more

Motivation 1.2

The company categorizes its total waste initially as controllable & uncontrollable waste. One major contributing factor for uncontrollable wastes is the voltage variations which last less than 3 seconds.

As an Engineer with a background of electrical installation the author selected this project to study the production waste generation activities and the mechanism that could be implemented to minimize it. This thesis proposes a new automated approach to detect the voltage variation and react accordingly. The brain of the controller is a peripheral interface controller (PIC).By using PIC the design was done with low cost comparatively. This device can be named as Short Period Voltage Dip Actuator (SPVDA) which helps automating the machines, leading to the following advantages.

- 1. No joints will be generated due to short period voltage variations(time less than 3 sec)
- 2. No waste generation due to consequence voltage variations
- 3. No re-processing time & hence man hours can be saved.
- 4. Reduce customer complaints and ac lk
- 5. No waste generation during the power changeover and vice versa and many more.
 - If the above voltage variation occurs successively within short periods • causing to have two joints within 10 meters it has to be disposed as waste. Implementation of the new actuator helps to eliminate this problem.
 - In the case of short period voltage variations such as voltage dips and momentary interruptions elastic tape damages can be seen and machine operators have to reconnect it after removing unwanted portions. Helps immensely in saving time, which results in higher productivity.

Block Diagram of the expected design of the controller



1.3 Goals

To achieve the final target the project work was broken further down to a set of goals, they are as follows.

1.3.1 Hardware Design

1.3.1.2 Selection of Relay (PCB driver)

Correct selection of the relay is very important because it drives the control PCB of the loom. Therefore several features need to be considered when choosing a relay such as switching rating, coil resistance, coil voltage, physical size & dielectric strength. As the relay was used for low voltage applications dielectric strength was not important. So that SPDT 5V DC/1A micro relay was selected. Features of the relay were.

- ✔ Coil rating ~ 5VDC .90mA
- Coil resistance 55 ohm
- Coil size 1-1/32"x3/8"x1/4"

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1.3.1.2 Selection of transistor (Relay Driver) Dissertations

Selection of transistor was very critical because the relay was driven by transistor which was initially controlled by the PIC. Out of many transistors available in the market correct one needs to be selected. General purpose C1815, NPN transistor was chosen [4] base on the calculations done [10].

1.3.1.3 Selection of optocoupler

Optocoupler was used to isolate the signals for protection and safety between a safe and a potential hazardous or electrically noisy environment. The interfacing of the optocoupler between digital or analog signal needs to be designed properly for proper protection and operation.

1.3.1.4 Selection of Peripheral Interface (PIC)

This is the controller of the design. There are varieties of PICs in the market. So that the required controller with right features needs to be selected (PIC16F877A).

1.3.1 Software Development

Instructions to the PIC should be given in hex. If the instructions are given in assembly language, it needs to be converted to hex by MPLAB software, also there is a facility to program using C with C compiler.

1.3.2 Implementation

- Control circuit was designed and installed on board
- ▶ Power supply of 5V & 9V to the PIC and AC/DC converter separately.
- ▶ Programmed the PIC using MPLAS Software & Programmer.
- Checked the functionality of the PIC by a simulation in MPLAB and then incorporated PIC to the control circuit and checked functionality of all possible inputs.

1.4 Achievements in brief

Completion of literature survey, integrated the designing of Short Period Power Dip actuator. Series of theoretical calculations were done to calculate and find the required components such as on-line resistor, pull down resistor to protect the optocoupler, input voltage stability and base limiting resistor of the driver transistor(C1815) of the relay circuit.

Fast Precision AC/DC converter which was built by cascading two LM101A operational amplifiers. It was selected among the other converters which can be done the same job, because it was a full wave rectifier and the response time was less than 54ms. The converter was converted AC voltage to DC analog voltage and it was sent it to PIC AN0 pin as an analogue input signal.

Machine operating state signal was supplied to the RC5 pin of the PIC through the optocoupler CYN-17-1. It was used to isolate power side from the control side. Selected PIC 16F877A offers lot of features like, interrupt handling capacity, A/D module, timers apart from that digital inputs & outputs. Components were ordered after designing. It took time to find the PIC because the one it was initially planned was very rare in the local market to purchase (PIC16F870). Then PIC16F877 which was available in the market was purchased. PIC program was written in assembly language. It took time because it was needed to learn more about assembly language to develop the program [1]. Writing the program was time consuming too. Finally the

program was developed and programmed in MPLAB, this was tested using MPLABSIM (MPLAB Simulator).

The PIC was debugged and programmed again. This was done many times until the correct program was obtained. Since PIC16F877A was flashed version, it could be programmed about 100,000 times without doing any damage to the PIC.



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Problem statement

2.1 Identification of machine states

Study about the machine operation and identifying problems was very useful to develop a system to minimize the effect due to the problem or problems. The weaving loom includes mainly three types of switches and two kinds of motors to run the loom. These are named as Tip switch, Stop switch, Start switch, Tip motor and main motor. Combinations of the operation of the switches and motors can be categorized in the table 2.1.

[Raw	Tip	Start	Stop	Tip	Main	Machine
State	power	switch	switch	switch	motor	motor	status
1	0	0	0	0	0	0	Stop
2	1	0	0	0	0	0	Stop
3	1∐⊺r	iversi	V O V	for 9 tur	$v_{2}1Sr$	T Onk	Tipping
4	1_1	0	-1	0	0	0	Stop
5	1210	cupii	c mes	es _o c I	pisen	aupns	Running
6	1WV	vw0ib.	mrø.ac	.lk1	0	0	Stop
7	1	1	1	0	0	1	Running
8	0	0	0	0	0	0	Stop
9	1 ·	0	0	0	0	0	Still Stop

Table 2.1-Combinations of machine states

State 4&6 can be explained that even though voltage is available machine is not able to run with Start switch itself. Tip switch is used to operate the machine at a moderate speed in order to setup or careful positioning of the moving parts in the machine. When Start switch is pressed with the Tip switch simultaneously & the machine can be run at its maximum set speed. The Stop switch is used to stop the machine and state 8 is very similar to the situation where power interruptions can be happened during the machine running. By seeing states 8 and 9 this situation can be identified as similar as to short period interruption or voltage dip situation and shutdown the machine. In the instance if the mechanism is developed to keep holding the two switches Stop and Tip simultaneously during the voltage variation or short period interruption (time t<3second) operation of the machine can be continued without having any production losses.

2.2 Behavior of the machine controller to the voltages

For the weaving machines electrical power for the controller starts from external transformer which is fitted into the machine. External transformer is capable of generating three levels of voltages. Those are 48, 27 & 18VAC and is fed into the weaving machine control PCB. The main motor contactor was energized by 48VAC through the internal relay system of the machine to control PCB and rest of the voltages (18VAC & 27VAC) were accommodated for the functions of balance activities of the control panel such as break, stop motions & other control circuits etc). The machines were operating with the CEB power and anytime voltage variations & interruptions can be happened. This will cause to stop the machine operations and consequently generate waste. So that investigations were done to find the behaviors of the machine controller and related motor contactor during the voltage variations. Trials were done with variac and experimental results were tabulated as following

tables. 2.2 and 2.3.

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AC I/P	% of Volt	48V AC	27V AC	17V AC	COMMENTS ON CONTROL PCB		
230V	100	47.1	26.5	17.5	Control functions of the machine PCB is ok		
225V	98	45.9	25.9	17.15	Do		
220V	96	44.9	25.35	16.8	Do		
215V	93	43.8	24.7	16.3	Do		
210V	91	42.7	24.12	16	Do		
205V	89	41.7	23.58	15.6	Do		
200V	87	40.6	22.96	15.2	Do		
195V	85	39.8	22.5	14.9	Card functions are satisfactory up to this point		
190V	83	38.99	21.84	14.45	Internal relays start to vibrate but card stays on condition		
185V	78.4	38.06	21.25	14.1	More noise but card functions are stable		
180V	78	36.94	20.66	13.72	Noise disappeared and the Power failure indicator LED (red) is ON and the card functions are stopped		

Table 2.2 - Behavior of Machine Controller to different Voltage Levels



Behaviors of the component for the different voltage levels

Table 2.3 - Behavior of other component to different Voltage Levels

As per the above results operation of the main motor contactor fails at 83% of single phase voltage, because of that voltage is less than the minimum threshold voltage (Appendix-E) of the coil (38.4VAC). The machine controller PCB functions were

disabled when the voltage reaches at 78% of single phase voltage, because of low control voltage of the PCB and de-energized the internal relays of the PCB. As a result of that main motor contactor would be de-energized and shut down the machine operation. The basic operation of the machine controller is explained by figure 2.1.



Figure 2.1-Schematic diagram for machine controller

2.3 Identification of the Problem

Due to the voltage variations production waste was generated significantly. Therefore the project was focused on minimization of waste due to voltage variations such as voltage dips. According to the survey was done there was a commercial device developed in UK was called high voltage traction capacitor device [8]. This device can be used to power the electrical devices in the case of voltage drops or in absence of power. But it is still in the development stage and also cost is high. Therefore still there is no any low cost mechanism to overcome this problem. But battery powered UPSs are one of perfect solutions. On average power consumption per loom is 1.5kW and plant capacity is 120 looms. Therefore at lease 180 kW UPS units are required to run the full capacity of the plant. But due to high capital cost it is not viable. Apart from the high capital cost following disadvantages were there.

- Frequent maintenance cost
- ► Fairly large space required
- Toxic waste
- Heat dissipation

Another one was fly wheel UPSs. This gives lot of advantages compared to the above. But the disadvantage is capital cost which is very much higher than the regular UPS systems.

In this research it was found approximately 50% of the power failures were less than 3 seconds and generated waste was 6% of the total waste. Therefore weaving looms in the Textile industry is very sensitive to the voltage variations and power quality problems and get stopped immediately. As a result of it, stop marks can be seen on the fabric tapes. It is the damage that can not be accepted by the customers.

2.3.1 Stop mark

The defect "stop mark" in the fabric tape was found on a continuous fabric due to the variation in tension building up along the yarn path from the yarn beam to elastic tape in case of machine stop.

The raw material (yarn) is wrapped on the aluminum beam which is about 40-70 kg loaded to the machine creel. The beam can be rotated freely with their center bearings and movement is controlled by the tension balance weights .If there is a sudden power failure or voltage variations happen free motion can be taken placed due to momentum of the beam. Therefore it causes a tension variation along the tapes. As a result of this a stop mark can be created. If there is a possibility to reset the machine within 3 seconds stored energy of the beam is enough to maintain the tension of the tape and creating stop mark can be minimized.

2.3 Objective of the project

The expectation of the projects was to reduce the waste and down time during the voltage variation. Since it finally affects the total revenue that can be generated from the plant.

This will require development of a new control system which should be facilitated to keep the machine start switches hold down during the voltage variations.

The new design involves digital control principles for practical implementation of control algorithms in a microcontroller unit (MCU). The following areas need to be focused.

- → How to detect voltage variations which effecting to the machine operation?
- What hardware components to be sourced and what to be produced to make the photo type design?
- Programming the microcontroller according to the control algorithm.
- ➤ How to obtain the experimental results?



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Hardware Design of the system

3.1 Microcontroller types for the application (MCU)

Single chip microcontroller device is ideal to control waste due to the voltage variations in many applications. The advantage of a MCU for the application is the MCUs program can be changed, revised by changing a few lines of text in the source code. This source code is then converted in to machine code by software compiler and is programmed into MCU.

The MC is a single chip computer. It operates as stored program machine that is it must be read its program code and data values from its memory in order to operate. Two common methods are used to accomplish this. One is called von Neumann architecture and has been employed in many MCUs. This method uses one data bus and memory space for both program code & data values. Saving cost but slowing down the code execution. The other approach is called Harvard architecture, separates the program code & data values into two memory structures allowing parallel loading of both at the same time. In this case data execution is essential therefore Harvard architecture can be selected during the selection of MCs.

3.2 Some related features of peripheral interface controller (PIC)

A microcontroller [2] differs from a microprocessor in many ways. First and most important is its functionality. In order to a microprocessor to be used, other components such as memory, or components for receiving and sending data must be added to it. On the other hand microcontroller is designed to be all of that in one. No other external components are needed for its applications other than an oscillator because all necessary peripherals are already build into it. Thus, it can be saved the time and space needed to construct devices.

3.3 Selection of Microcontroller unit (PIC)

Different types of Peripheral Interface Units (PICs) are available in the market. In this thesis PIC16F series was considered. Features that considered for the application are given in the following table 3.1.

Device	Program memory Single word instructions	Data memory SRAM (bytes)	I/O Pins	Operating speed (MHz)	10 Bit A/D Modules	Timers 8/16 Bits	I/O Ports
PIC16F84A	1024	68X8	13	20	-	1	2
PIC16F85	1024	128x8	15	20	4ch;8bit	1	2
PIC16F870	2048	128x8	22	20	5ch;8	3	3
PIC16F871	2048	128x8	33	20	8ch;8	3	4(A,B.C,D)
PIC16F86	2048	128X8	15	20	4ch;8bit	1	2
PIC16F873A	4096	192	22	20	5ch;8bit	2/1	3
PIC16F874A	4096	192	33	20	8ch:8bit	2/1	5
PIC16F876A	8192 .	368	22	20	5ch:8bit	2/1	3
PIC16F877A	8192	368	33	20	8ch:8bit	2/1	5

University Table 3.1- PIC16F Device Features Electronic Theses & Dissertations

According to the above comparison in PIC16F87XA series PIC16F877A has 8k instructions of program memory, 368 bytes of SRAM data memory, 33 I/0s, 5 Ports, 10 bit A/D modules, two 8 bit timers and many more. But it was required inputs & outputs for software development such as,

- Three Ports A,B and C
- Two Analog modules
- Two digital outputs
- One digital input

Therefore except PIC16F84A all the other Peripheral Interface Units can be used for the software development of this project. But on top of that priority must be given to the product which is available in the market due to the time constrain. PIC16F877A is one of the largest program memory capacity chip available in the local market. Therefore PIC16F877A [2,5] was selected as the controller of the proposed system.

Pin Diagram



Figure 3.1 - PIC16F877 Pin Diagram

3.3.1 THE PIC16F887A BASIC FEATURES

- Architecture
 - Only 35 instructions to learn
 - All single-cycle instructions except branches
- Operating frequency 0-20 MHz
- Precision internal oscillator
 - Factory calibrated
 - Software selectable frequency range of 8MHz to 31KHz

• Power supply voltage 2.0-5.5V

- Consumption: 220uA (2.0V, 4MHz), 11uA (2.0 V, 32 KHz) 50nA (stand-by mode)
- Power-Saving Sleep Mode
- Brown-out Reset (BOR) with software control option
- 33 input/output pins
 - High current source/sink for direct LED drive
 - Software and individually programmable *pull-up* resistor
 - Interrupt-on-Change pin
- 8K ROM memory in FLASH technology
 - Chip can be reprogrammed up to 100.000 times
- In-Circuit Serial Programming Option
 - Chip can be programmed even embedded in the target device
- 256 bytes EEPROM memory
 - Data can be written more than 1.000.000 times
- 368 bytes RAM memory of Moratuwa, Sri Lanka.
- A/D converter: Electronic Theses & Dissertations
 - o 08-channelswww.lib.mrt.ac.lk
 - 10-bit resolution
- 3 independent timers/counters
- Watch-dog timer
- Analogue comparator module with
 - Two analogue comparators
 - Fixed voltage reference (0.6V)
 - Programmable on-chip voltage reference
- PWM output steering control
- Enhanced USART module
 - Supports RS-485, RS-232 and LIN2.0
 - o Auto-Baud Detect
- Master Synchro nous Serial Port (MSSP)
 - Supports SPI and I2C mode



3.3.2 PIN Assignment of PIC16F877A

Pin Name	DIP Pin#	PLCC Pin#	QFP Pin#	l/O/P Type	Buffer Type	Description
OSC1/CLKI OSC1 CLKI	13	14	30	1	ST/CMOS ⁽⁴⁾	Oscillator crystal or external clock input Oscillator crystal input or external clock source input. ST buffer when configured in RC mode. Otherwise CMOS. External clock source input. Always associated with pin function OSC1 (see OSC1/CLKI, OSC2/CLKO pins).
OSC2/CLKOUT OSC2 CLKO	14	15	31	0		Oscillator crystal or clock output. Oscillator crystal output. Connects to crystal or resonator in Crystal Oscillator mode. In RC mode, OSC2 pin outputs CLKO, which has 1/4 the frequency of OSC1 and denotes the instruction cycle rate.
MCLR/VPP MCLR VPP	1	2	18	I/P	ST	Master Clear (input) or programming voltage (output). Master Clear (Reset) input. This pin is an active low RESET to the device. Programming voltage input.
						PORTA is a bi-directional I/O port.
RA0/AN0 RA0 AN0	2	3	19	1/0 1	TTL	Digital I/O. Analog input 0.
RA1/AN1 RA1 AN1	3	4	20 Univ		TTL	Digital I/O. Analog input 1.
RA2/AN2/VRFF-/CVREF RA2 AN2 VREF- CVREF	4	5	E ²¹ ec www	v.lib	c These mrt.ac.1	Analog input 2. A/D reference voltage (Low) input. Comparator VREF output.
RA3/AN3/VREF+ RA3 AN3 VREF+	5	6	22	/O 	TTL	Digital I/O. Analog input 3. A/D reference voltage (High) input.
RA4/T0CKI/C1OUT RA4 T0CKI C1OUT	6	7	23	1/0 1 0	ST	Digital I/O – Open drain when configured as output. Timer0 external clock input. Comparator 1 output.
RA5/SS/AN4/C2OUT RA5 SS AN4 C2OUT	7	8	24	I/O I I O	TTL	Digital I/O. SPI slave select input. Analog input 4. Comparator 2 output.
Legend: I = input	O = outp — = Not	ut used	. 	ίΟ = inpu ITL = TT	it∕output L input	P = power ST = Schmitt Trigger input

Note 1: This buffer is a Schmitt Trigger input when configured as an external interrupt.

This buffer is a Schmitt Trigger input when used in Serial Programming mode.
This buffer is a Schmitt Trigger input when configured as general purpose I/O and a TTL input when used in the Parallel Slave Port mode (for interfacing to a microprocessor bus).

4: This buffer is a Schmitt Trigger input when configured in RC oscillator mode and a CMOS input otherwise.

Table 3.2 - Pin Assignment PIC877A

Pin Name	DIP Pin#	PLCC Pin#	QFP Pin#	I/O/P Type	Buffer Type	Description	
						PORTB is a bi-directional I/O port. PORTB can be soft- ware programmed for internal weak pull-up on all inputs.	
RB0/INT RB0 INT	33	36	8	1/O 1	TTL/ST ⁽¹⁾	Digital I/O. External interrupt.	
RB1	34	37	9	I/O	ΤŤL	Digital I/O.	
RB2	35	38	10	I/O	TTL	Digital I/O.	
RB3/PGM	36	39	11		TTL		
RB3 PGM			-	1/0 1/0		Digital I/O. Low voltage ICSP programming enable pin.	
RB4	37	41	14	I/O	TTL	Digital I/O.	
RB5	38	42	15	I/O	TTL	Digital I/O.	
RB6/PGC	39	43	16		TTL/ST ⁽²⁾		
RB6 PGC				1/0 1/0		Digital I/O. In-Circuit Debugger and ICSP programming clock.	
RB7/PGD	40	44	17		TTL/ST ⁽²⁾		
RB7 PGD				1/0 1/0		Digital I/O. In-Circuit Debugger and ICSP programming data.	
			-		1	PORTC is a bi-directional I/O port.	
RC0/T1OSO/T1CKI RC0 T1OSO T1CKI	15	16	32	1/0 0	ST	Digital I/O. Timer1 oscillator output. Timer1 external clock input.	
RC1/T1OSI/CCP2	16	18 [135	ersity	ofstlor	atuwa, Sri Lanka.	
RC1 T1OSI) E	lect		Theses	Digital I/O. Timer1 oscillator input Capture2 input Compare2 output PWM2 output	
	17	10 V	1	lib.r	nrt.æc.lk		
RC2 CCP1		13	30	1/0 1/0		Digital I/O. Capture1 input/Compare1 output/PWM1 output.	
RC3/SCK/SCL	18	20	37		ST		
RC3 SCK SCL				1/0 1/0 1/0		Digital I/O. Synchronous serial clock input/output for SPI mode. Synchronous serial clock input/output for I ² C mode.	
RC4/SDI/SDA	23	25	42		ST		
RC4				I/O		Digital I/O.	
SDI						SPI data in. I ² C data I/O	
SUA Dociono	24	0.0	10		CT.		
RC5/SDO RC5 SDO	24	20	: 43 	1/0 0		Digital I/O. SPI data out.	
RC6/TX/CK	25	27	44		ST		
RC6				1/0		Digital I/O.	
TX CK				0 1/0		USART asynchronous transmit. USART 1 synchronous clock.	
RC7/RX/DT	26	29	1		ST		
RC7				1/0		Digital I/O,	
DT				1/0		USART asynchronous receive. USART synchronous data.	
Leaend: L= input	L O ≂ outr			/0 = inn	it/output	P = power	
Davier , what	- = Not	used		TTL = TT	Linput	ST = Schmitt Trigger input	

Note 1: This buffer is a Schmitt Trigger input when configured as an external interrupt.

2: This buffer is a Schmitt Trigger input when used in Serial Programming mode.

3: This buffer is a Schmitt Trigger input when configured as general purpose I/O and a TTL input when used in the Parallel Slave Port mode (for interfacing to a microprocessor bus).

4: This buffer is a Schmitt Trigger input when configured in RC oscillator mode and a CMOS input otherwise.

Table 3.3 - Pin Assignment PIC877A

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PIC877A Pin out Description (Continued)

Pin Name	DIP Pin#	PLCC Pin#	QFP Pin#	l/O/P Type	Buffer Type	Description	
						PORTD is a bi-directional I/O port or parallel slave port when interfacing to a microprocessor bus.	
200/PSPN	19	21	38	ļ	ST/TTL ⁽³⁾		
RD0				-1/O		Digital I/O.	
PSP0			ļ	1/O		Paraliel Slave Port data.	
D1/PSP1	20	22	39		ST/TTL ⁽³⁾		
RD1				I/O		Digital I/O.	
PSP1		1	1	NO I		Parallel Slave Port data.	
RD2/PSP2	21	23	40		ST/TTL ⁽³⁾		
RD2				1/0		Digital I/O. Demilal Slave Port deta	
PSP2				1/0	(2)	Parallel Slave Port data.	
₹D3/PSP3	22	24.	41		ST/TTL(3)		
RD3				1/0		Digital I/O. Desetiel Stave Port data	
PSP3				1/0	(2)	Parallel Slave Fort data.	
RD4/PSP4	27	30	2		ST/TTL ⁽³⁾	Distriction	
RD4				1/0		Digital I/O. Parallol Slave Port data	
PSP4				1/0	(2)	Paraller Slave Poir data.	
RD5/PSP5	28	31	3		ST/TTL ⁽³⁾		
RD5				1/0		Digital I/O. Develial Stave Part data	
PSP5			i	1/0	(3)	Farallel Slave Fort data.	
RD6/PSP6	29	32	4	1.00	ST/TTL ⁽³⁾	Divite 1/O	
RD6				1/0		Digital I/O. Parallel Stave Port data	
PSP6					(3)		
RD7/PSP7	30	33	5		STATES	Diaital VO	
RD7	ficana.	ТТ		1/0	C 7 (Digital I/O. Parallel Slave Port data	
PSP7	- Jan	U1	nivei	ISINY	PI Mor	DODTE is a bi directional I/O part	
		E1	hotro	inio	Thoras	PORTE is a bi-directional tro port.	
RE0/RD/AN5	8	9	25	JIIIC	I STATION	a Dissertations	
RE0		XXZ	ww 1	1/0	int ac lk	Digital I/O. Road control for parallel slave port	
RD		vv			u t.uv.m	Analog input 5	
AN5	_			'	OT (TT) (3)	i i i i i i i i i i i i i i i i i i i	
RE1/WR/AN6	9	10	26	10	SHIL	Digital VO	
RE1				1/0		Write control for parallel slave port.	
ANG				i	İ	Analog input 6.	
	10	11	27		ST/TTI (3)		
REZ/US/AN/	10	1 11	21	1/0	- On the state of	Digital I/O.	
				″ĭ		Chip select control for parallel slave port.	
AN7	1					Analog input 7	
Vss	12,31	13.34	6,29	Р		Ground reference for logic and I/O pins.	
Von	11 32	12 35	7 28	P		Positive supply for logic and I/O pins.	
VDD		4.4.7	10.10	+	+	These pins are not internally connected. These pins	
NG		28.40	33.34			should be left unconnected.	
Looped: Imioput		L	,		. I	P = nower	
Legend, i = input 0 = output		tucod	TTI = TTI input			ST = Schmitt Trigger input	

Note 1: This buffer is a Schmitt Trigger input when configured as an external interrupt.

2: This buffer is a Schmitt Trigger input when used in Serial Programming mode.

3: This buffer is a Schmitt Trigger input when configured as general purpose I/O and a TTL input when used in the Parallel Slave Port mode (for interfacing to a microprocessor bus).

4: This buffer is a Schmitt Trigger input when configured in RC oscillator mode and a CMOS input otherwise.

Table 3.4 - Pin Assignment PIC877A

04346

3.3.3 Device block diagram



Fig 3.2 - Internal architecture of PIC microcontroller

Above Figure 3-2 describe the device block diagram of the 16FPIC877A

3.3.4 Program memory organization

There are three memory blocks in each of thePIC16F87XA devices. The program memory and data memory has separate buses so that concurrent access can be occurred. The program memory can be read internally by user code The PIC16F87XA devices have a 13-bit program counter capable of addressing an 8K word x 14 bit program memory space. The PIC16F876A/877A devices have 8K

1.00

words x 14 bits of Flash program memory, The below fig 3.3 is the memory allocations of the PIC16F877A.



Program memory map and stack

Fig 3.3 - Memory map

3.3.5 Data Memory Organization

The data memory is partitioned into multiple banks which contains the General Purpose Registers and the Special Function Registers. Bits RP1 (Status<6>) and RP0 (Status<5>) are the bank select bits. Each bank extends up to 7Fh (128 bytes). The lower locations of each bank are reserved for the Special Function Registers. Above the Special Function Registers are General Purpose Registers, implemented as static RAM. All implemented banks contain Special Function Registers. Some frequently used Special Function Registers from one bank may be mirrored in another bank for code reduction and quicker access.

RP1:RP0	Bank
00	0
01	1
10	2
11	3

Table 3.5 - Bank selection

3.3.6 Oscillator

Oscillator circuit is used to provide a micro controller with a clock. Clock is needed so that micro controller could be executed a program or program instructions.

3.3.6.1 Types of oscillators

PIC16F877A can be worked with four different configurations of an oscillator. Since configurations with crystal oscillator and resistor-capacitor (RC) are the ones that are used most frequently. Microcontroller type with a crystal oscillator has in its designation XT, and a microcontroller with resistor-capacitor pair has a designation RC. This is important because during the time of purchasing a MC need to mention the type of oscillator. The user can program two configuration bits ((FOSC1 and FOSC0) to select one of these four methods.

- ► LP Low-Power Crystal
- ➤ XT Crystal/Resonator
- ► HS High-Speed Crystal/Resonator
- RC Resistor/Capacitor

3.3.6.2 XT Oscillator

Crystal oscillator is kept in metal housing with two pins where you have written down the frequency at which crystal oscillates. One ceramic capacitor whose other end is connected to the ground needs to be connected with each pin.

Oscillator and capacitors can be packed in joint case with three pins. Such element is called ceramic resonator and is represented in charts like the one below. Center pins of the element are the ground, while end pins are connected with OSC1 and OSC2 pins on the microcontroller. When designing a device, the rule is to place an oscillator nearer a microcontroller, so as to avoid any interference on lines on which

microcontroller is receiving a clock. Following figures shows how to connect both oscillator options using a ceramic resonator is normally less expensive. This project 4MHz crystal oscillator has been used because it is the most accuracy one out of the others.



Figure 3.4 - Oscillator connection Electronic Theses & Dissertations www.lib.mrt.ac.lk

3.3.6.3 RC Oscillator

For timing insensitive applications, the "RC" device option offers additional cost savings. The RC oscillator frequency is a function of the supply voltage, the resistor (REXT) and capacitor (CEXT) values, and the operating temperature. In addition to this, the oscillator frequency will vary from unit to unit due to normal process parameter variation. Furthermore, the difference in lead frame capacitance between package types will also affect the oscillation frequency, especially for low CEXT values. The user also needs to take into account variation due to tolerance of external R and C components used. Figure 3.5 shows how the R/C combination is connected to the PIC16F87X.



RC Oscillator mode



Figure 3.5 - RC Oscillator

For the design purpose ceramic disc capacitors for the crystal oscillator of the PIC16F877A can be taken from the following table 3.6

Osc Type	Crystal Freq.	Cap. Range C1	Cap. Range C2	a, Sri Lanka issertations
LP	32 kHz	w. 133 pFnrt.	C. 33 pF	
	200 kHz	15 pF	15 pF	
XT	200 kHz	47-68 pF	47-68 pF	
	1 MHz	15 pF	15 pF	
	4 MHz	15 pF	15 pF	
HS	4 MHz	15 pF	15 pF	
	8 MHz	15-33 pF	15-33 pF	
	20 MHz	15-33 pF	15-33 pF	

Capacitor selection for crystal oscillator

Table 3.6 - Capacitor selection

Following a supply, oscillator starts oscillating. Oscillation at first has an unstable period and amplitude, but after some period of time it becomes stabilized. The signal of an oscillator clock after receiving the supply of microcontroller is given below





Signal of an oscillator clock after receiving the supply of a microcontroller Figure 3.6 - Oscillator clock signal

To prevent such inaccurate clock from influencing microcontroller's performance, we need to keep the microcontroller in reset state during stabilization of oscillator's clock. Diagram above shows a typical shape of a signal which microcontroller gets from the quartz oscillator.

3.3.7 High speed 10 bit A/D converter

The Analog-to-Digital (A/D) converter module has eight inputs for the PIC16F877A. The analog inputs charges a sample and hold capacitor. The output of the sampler and hold capacitor is the input into the converter. The converter then generates a digital result of this analog level via successive approximation. The A/D conversion of the analog input signal results in a corresponding 10 bit digital number. The A/D module has high and low voltage reference input that is software selectable to some combination of V_{DD} , V_{SS} , and RA2 or RA3.

A new feature for A/D converter is the addition of programmable acquisition time. This feature allows the user to select a new channel for conversion and to set the GO/DONE bit immediately. When the GO/DONE bit is set the selected channel is sampled for the programmed acquisition time before a conversion is actually started.

3.3.7.1 Ports

Term "port" refers to a group of pins on a microcontroller which can be accessed simultaneously, or on which we can set the desired combination of zeros and ones, or read from them an existing status. Physically, port is a register inside a microcontroller which is connected by wires to the pins of a microcontroller. Ports represent physical connection of Central Processing Unit with an outside world. Microcontroller uses them in order to monitor or control other components or devices. Due to functionality, some pins have twofold roles. Selection of one of these two pin functions is done in one of the configuration registers.



Figure 3.7 -- I/O Unit

3.3.7.2 Input Output ports

Those locations It has just been added are called "ports". There are several types of ports input, output or bidirectional ports. When working with ports, first of all it is necessary to choose which port we need to work with, and then to send data to, or take it from the port.

In order to synchronize the operation of I/O ports with the internal 8-bit organization of the microcontroller, they are, similar to registers, grouped into five ports denoted by Λ , B, C, D and E. All of them have several features in common. When working with it the port acts like a memory location. Something is simply being written into or read from it, and it could be noticed on the pins of the microcontroller.

3.3.7.3 PORT and TRIS

For practical reasons, many I/O pins are multifunctional. Every port has its 'satellite'. i.e. the corresponding TRIS register: TRISA, TRISB, TRISC etc. which determines the performance of port bits, but not their contents.





Figure 3.8-Port and Tris

All port pins can be designated as input or output, according to the needs of a device that's being developed. In order to define a pin as input or output pin, the right combination of zeros and ones must be written in TRIS register. If the appropriate bit of TRIS register contains logical "1", then that pin is an input pin, and if the opposite is true, it's an output pin. Every port has its proper TRIS register. Thus, port A has TRISA, and port B has TRISB. Pin direction can be changed during the course of work which is particularly fitting for one-line communication where data flow constantly changes direction. PORTA and PORTB state registers are located in bank 0, while TRISA and TRISB pin direction registers are located in bank 1.

3.3.8 TIMER TMR1

Timer TMR1 module is a 16-bit timer/counter, which means that it consists of two registers (TMR1L and TMR1H). It can be counted up 65.535 pulses in a single cycle, i.e. before the counting starts from zero. These registers can be read or written to at any moment. In case an overflow occurs, an interrupt is generated if enabled. The timer TMR1 module may operate in one of two basic modes, that is as a timer or a counter. Unlike the TMR0 timer, both of these modes have additional functions. The TMR1 timer has following features:
- 16-bit timer/counter register pair;
- Programmable internal or external clock source;
- ➤ 3-bit prescaler;
- Optional LP oscillator;
- Synchronous or asynchronous operation;
- Timer TMR1 gate control (count enable) via comparator or T1G pin;
- Interrupt on overflow;
- Wake-up on overflow (external clock); and
- Time base for Capture/Compare function.

3.4 Phototransistor Opticoupler

The CNY17 contains a light emitting diode optically coupled to a photo-transistor. It is packaged in a 6-pinDIP package and available in wide-lead spacing option and lead bands option. Collector-emitter voltage is above 70 V. Response time.(tr), is typically 5 µs and minimum CTR is 40% at input current of 10 mA.





It is most important to note that there is no direct electrical connection between the left side of the optocoupler and the right side. The left side is the connection to the outside world. Anything could be happened on that side. The right side is the delicate internal workings of our device.

The optocoupler will help prevent some kinds of electrical damage to the device. However, as with any engineering object, it has its limits. The LED part of the optocoupler is very much like the LEDs that anybody is familiar with. LEDs are tough and not easily damaged, however it is possible to burn them out. If the LED is made to pass too much current, it will be burnt out. The external resistor will be connected to anode to prevent the damage. Also, if lightning strikes the optocoupler a spark could possibly go across the terminals from left to right and this could cause damage to the device too

Absolute Maximum Ratings:

	Parameter	Symbol	Rating	Unit
	Peak forward current	I _{RM}	1	A
	Reverse voltage	V _R	6	<u>V</u>
Input	Power dissipation	PD	70	mW
I	Collector-emitter voltage	V _{CEO}	70	V
• • • • • • • • • • • • • • • • • • •	Emitter-collector voltage	V _{ECO}	6	V
i	Collector-base voltage	V _{CBO}	60	V
	Emitter-base voltage	V _{EBO}	6	V
Output	Collector current	IC	50	mA
	Collector power dissipation	P _C	150	mW
	Total power dissipation	P _{tot}	200	mW
1	Isolation voltage 1 minute	Viso	5300	Vrms
		V _{iso}	7500	Vpk
	Operating temperature	T _{opr}	-55 to +100	⁰ C
	Storage temperature	T _{stg}	-55 to +125	⁰ C
	Soldering Temperaturevers	y of solo	atuw260 ri La	nka. ^u C

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 Table 3.7 - Optocoupler Parameters

Electrical Characteristics:

	Parameter	Symbol	Conditions	Min	Тур	Max	Unit
	Forward voltage	VF	IF=20mA	-	1.2	1.4	V
,	Peak forward voltage	VFM	IFM=0.5A	-		3.5	V
Input	Reverse current	R	VR-4V		-	10	$\mu\Lambda$
	Terminal capacitance	Ct	V=0,f=1kHZ		30	-	pF
Output	Collector dark current	ICEO	VCE=20V	-	-	0.1	μΑ
Transf	Current transfer ratio	CTR	IF=10mA, VCE=5V	40		80	%
Charac taristes	Collector-emitter saturation voltage	VCE(sat)	IF=10mA ,Ic=2.5mA	-	0.1	0.4	V
	Isolation resistance	Riso	DC500V	$5x10^{10}$	1011		ohm
	Floating capacitance	Cf	V=0 , f=1 MHZ	-	0.6	1.0	Pf
	Cut off frequency	T	Vcc=5V, Ic=2mA,RL-100ohm	-	80	-	kHz
	Response time (Rise)	Tr	Vce=2V,Ic=2mA	-	5	20	μs
	Response time (Fall)	tf	RL=100ohm	-	4	20	μs

Table 3.8 - Optocoupler Electrical Characteristics



Precision AC/DC Converter

Figure 3.10 - Fast AC/DC Converter

This precision rectifier functions [3] somewhat different. The input signal is applied through R1to the summing node of an inverting operational amplifier. When the signal is positive, D1 is forward biased and develops an output signal across R2. As with any inverting amplifier, the gain is R2/R1. When the signal goes negative, D1 is non-conducting and there is no output. However, a negative feedback path is provided by D2. The path through D2 reduces the negative output swing to -0.7V, and prevents the amplifier from saturating.

Since* the LM101A is used as an inverting amplifier, feed forward compensation can be used. Feed forward compensation increases the slew rate to 10 V/ms and reduces the gain error at high frequencies. This compensation allows the half wave rectifier to operate at higher frequencies than the previous circuits with no loss in accuracy.

The addition of a second amplifier converts the half wave rectifier to a full wave rectifier. As is shown in Figure 3.10, the half wave rectifier is connected to inverting amplifier A2. A2sums the half waves rectified signal and the input signal to provide a full wave output. For negative input signals the output of A1 is zero and no current

thows through R3. Neglecting for the moment C2, the output of $\Lambda 2$ is $-\frac{R_7}{R_6} \times E_{IN}$

For positive input signals, A2 sums the currents through R3 and R6; and E_{otr} =

$$R_7 \left[\frac{E_{IN}}{R_3} - \frac{E_{IN}}{R_6} \right]$$
 If R₃ is 1/2 R₆, the output is $\frac{R_7}{R_6} \times E_{IN}$. Hence, the output is

always the absolute value of the input.

Filtering, or averaging, to obtain a pure dc output is very easy to do. A capacitor, C2, placed across R7 rolls off the frequency response of A2 to give an output equal to the average value of the input. The filter time constant is R_7C_2 , and must be much greater than the maximum period of the input signal. For the values given in Figure 3.10, the time constants about 0.22 seconds. This converter has better than1% conversion accuracy to above 100 kHz and less than1% ripple at 20 Hz. The output is calibrated to read the RMS value of a sine wave input.

As with any high frequency circuit some care must be taken during construction. Leads should be kept short to avoid stray capacitance and power supplies bypassed with 0.01 μ F disc ceramic capacitors. Capacitive loading of the fast rectifier circuits must be less than 100pF or decoupling becomes necessary. The diodes should be reasonably fast and film type resistors used. Also, the amplifiers must have low bias currents.

3.6 Calculations of the components

3.6.1 Pull down resistor of the optocoupler (R_L) [9]



Figure 3.11 - Pull down Resistor

Supply voltage V	University of M Electronic These	foratuwa, Sri Lanka. es & Dissertations	
Operating temperature	www.lib.mrt.ac.	$= -55$ to 100 $^{\circ}$ C	
Typical CTR value selecte	d as 100% at $I_F = 10$	0mA At -20 to $+$ 60 0 C	
From the graph(see Optoc	oupler data sheet in ap	ppendix-G)	
CTR undergoes a change i	n between +5% to -12	2%	
Assuming a 10year servic	e life period		
allowances for additional	CTR reduction	= 20%	
allowances for additional	CTR safe value	-25%	
Therefore CRT _{min}		= 100% x(0.88)x(0.80)x(0.75	;)
		52.8%	
Referring the PIC Data she	eet $V_{\rm IL}$ for the smith t	rigger input is 1V and $V_{\rm HI}$ is 4VD	С
Max input low voltage to l	$PIC(V_{IL})$	$-\mathrm{V}_{\mathrm{IL}} \leq 1V$	
Input low current (IIL)		™ 1µA	

 I_{CEO} Therefore it is negligible, I_L

32

 $\approx 0.1 \mu A$

 $= I_{IL}$

For Max value of R_L

 $R_{L} \left\langle \frac{V_{IL}}{I_{IL}} = \frac{1V}{1 \times 10^{-6}} = 1M\Omega$ $= 1 M\Omega$

Therefore Max R_L

For safety high state at output $V_{\rm IH}$

$$V_{\rm HI} \quad \rangle \frac{V_{\rm HI}}{I_L} = \frac{4V}{5.3mA} = 188.6\Omega$$

Resistance of the pull down resistor RL is vary between $1 M\Omega \langle R_L \rangle$ (188.6 Ω

Therefore Pull down resistor R_L can be selected as $1k\Omega$

3.6.2 Current limiting resistor(Chopping resistor) (R_V) [9]

The R_L – 1k is selected and 20% safety is computed to the minimum V_{IH} in respect of the high state

 $VIH=VIH\times 20\% = 2.4V$

This will then permit IC. IF and the chopping resistor RV at the input of the

optocoupler to be determined. University of Moratuwa, Sri Lanka. $I_{C} = I_{L} > \frac{2.4}{R_{t}} = 2.4mA$, where $R_{L} = 1k\Omega$. Where $R_{L} = 1k\Omega$.

$$I_{\rm F}$$
 $> \frac{2.4mA}{CTR} = \frac{2.4}{0.53} = 4.5 \,\rm{mA}$

Where Forward voltage of the IR diode VF=1.2V

$$R_V \rangle \frac{V_{CC} - V_F}{4.5mA} = \frac{68 - 1.2}{4.5 \times 10^{-3}}$$

 R_V $14.8k\Omega$

Therefore Chopping resistor can be selected as $15k\Omega$

······································	
R	1kΩ
	the second se
R _V	15kΩ

Table 3.9 – Resistors of the optocoupler circuit

3.6.3 Current limiting resistor (R_b) and Transistor (Tr) [10]



Figure 3.12 - Current limiting resistor at RB1

(a) Selection of transistor

Resistance of the relay coil University of Mor 55 ohm Sri Lanka. Max current out from the PIC (I_{PIC}) ctronic Theses 25 mAssertations Supply voltage V_{CC} Transistor at saturation I_C is max when V_{CE}=0, R_{CE}=0

Therefore Load current I_C at transistor saturation $-\frac{V_{CC}}{R_L} = \frac{5}{55}$

= 91mA

Therefore transistor must have

 $I_{C(max)}$ >91mA

$$\min h_{EF} \geq \frac{5 \times I_{C} \cdot_{load}}{Max(Current(I_{PR}))}$$
$$\min h_{FE} \geq \frac{5 \times 91mA}{25mA} \geq 18.2$$

Therefore C1815, NPN transistor was selected as min $h_{EF} = 70$ and $I_{C}(max) = 150 m A$



(b) Selection of current limiting resistor R_B

$$R_{B} = \frac{V_{S} \times h_{FE}}{5 \times I_{C}}$$
 where V_S is supply voltage of the PIC

For this application supply voltage of the PIC and transistor circuit is same. So that $V_S = V_{CC}$ and above formula can be re-arranged as

 $R_{\scriptscriptstyle B}=0.2\times h_{\scriptscriptstyle FE}\times R_{\scriptscriptstyle L}$

 $= 0.2 \times 70 \times 55 = 770$ ohm

Therefore Current limiting resistor RB was selected as 820 ohm

(C) Current limiting resistor R1 output port RB2



For safe operation Id=15mA and Vd =1.7V

Output voltage of the PIC = 5V

Therefore

Id $= \frac{5 - Vd}{R1} = \frac{5 - 1.7}{R1}$ R1 = 220 0hm

Limiting resistor

Software Design of the system

4.1 Introduction

The ability to communicate is of great importance in any field. However, it is only possible if both communication partners know the same language, i.e follow the same rules during communication. Using these principles as a starting point, we can also define communication that occurs between microcontrollers and man. Language that microcontroller and man use to communicate is called "assembly language". The title itself has no deeper meaning, and is analogue to names of other languages, ex. English or French. More precisely, "assembly language" is just a passing solution. Programs written in assembly language must be translated into a "language of zeros and ones" in order for a microcontroller to understand it. "Assembly language" and "assembler" are two different notions. The first represents a set of rules used in writing a program for a microcontroller, and the other is a program on the personal computer which translated into "zeros" and "ones" is also called "machine language".



Figure 4.1-The process of communication between a man and a microcontroller

Physically, "**Program**" represents a file on the computer disc (or in the memory if it is read in a microcontroller), and is written according to the rules of assembler or some other language for microcontroller programming. Man can understand assembler language as it consists of alphabet signs and words. When writing a program, certain rules must be followed in order to reach a desired effect. A Translator interprets each

instruction written in assembly language as a series of zeros and ones which have a meaning for the internal logic of the microcontroller.

4.2 Method

Before writing the assembly codes it is convenient to draw a flow chart for the whole program. The mechanism develop to recover the production waste (SPPDA) of the weaving machine using embedded microcontroller is developed as per the flow chart in figure 4.2, Practical testing was done in the factory at Biyagama.

4.3 Algorithm

The algorithm used for developing embedded programming as follows

- Implement the microcontroller based integrated control system
- The permissible values obtained from practical test and results were entered as reference value in microcontroller unit.
- University of Moratuwa, Sri Lanka.
- Start the machine at rated condition heses & Dissertations
- Competition are made between measured values with reference value.
- ✓ If $V_{measured} \le V_{ref}$ then generate signal to operate the relay where $V_{measured}$ and V_{ref} are connected to AN0 and AN1 respectively.
- ✓ If time t ≥ 3 sec & $V_{measure} \langle V_{ref} \rangle$ stop the relay function and shut down the machine.
- Prototype model is developed and tested on a machine. The microcontroller base control system (SPPDA) respond to all types of voltage variations perfectly specified by and reenergized the relay after the specified time delay (3second).

4.3.1 Software development flowchart



Figure 4.2 - Flow chart for software development

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4.4 Resolution and Time Calculation

4.4.1 Resolution of the Analog signal

Speed of the crystal used for the PIC	=4 MHz
Time period per instruction	=1µsecond
Machine controller functions fail voltage	=180VAC
Reference voltage at pin AN0	= 5VDC
Voltage at the pin $\Lambda N1$	$-\frac{5 \times 180}{230} = 3.9VDC$
Required bits for the A/D conversion	=10 bits
Voltage resolution	$\frac{5}{\left(2^{10}-1\right)} \approx 5 \mathrm{mV/Di}$

Therefore resolution of the analogue conversion is 5mV/Div

4.4.2 Acquisition time for the Analog module atuwa, Sri Lanka



Figure 4.3 – Analog module for Acquisition time

As per the above figure 4.3 Acquisition time TACQ = Amplifier setting time

+Hold capacitor charging time

+Temperature coefficient

V

TACQ==TAMP+TC+TCOFF

 $=2\mu s+TC+[Temp-25^{\circ}C](0.05\mu s/^{\circ}C)$

 $TC = C_{HOLD}(R1C + Rss + Rs)ln(1/2047)$

As per the Figure 4.3 resistors and capacitor values for the equivalent circuit to calculate acquisition time related to analog input AN0 and AN1are respectively as follows. The Rs value which is output resistance of the input circuit of the analog input AN0 is approximately zero because output impedance of the OP amp is negligible. When AN1 is considered two possible values can be considered which are at half preset (3.9V) and at full preset.

(a) Rs 0Ω , R1C=1k Ω , Rss=7k Ω from the graph of fig 4.3 at 5V

(b) Rs=22k\Omega , R1C=1k\Omega and Rss=7k\Omega @5VDC and CHOLD=120pF

(c) Rs=100k Ω , R1C=1k Ω and Rss=7k Ω @5VDC and CHOLD=120pF

According to the above equation calculated TACQ at AN0 is 10.55 μ s and offset value of the pre-define general purpose register for the acquisition delay in the waiting loop in the program is 254 and likewise TACQ at AN1 is 30.6 μ s and offset value is 248. But maximum Rs value could be taken as 100k Ω at full preset position. So that calculated TACQ at AN1 is 103 μ s and related offset value is 231.when the assumptions are taking to calculate the Rs some errors can be happened. Therefore safe value for the offset can be selected as 231 to get highest acquisition time.

4.4.3 Basic operation of the program

- AC/DC converter monitor present voltage level in the main supply which is supplied to the analog input AN0 at pin5 of the microcontroller portA and it could be varied in between 0V to 5V during the voltage variation or interruption.
- 2) Reference analog voltage 3.9VDC which is the threshold voltage level of the woven machine controller is applied to the AN1 at pin no3 in port A
- 3) As usual V_{DD} and V_{SS} of the microcontroller are connected to 0VDC and 5VDC respectively.
- 4) The machine run state is monitored by the optcoupler circuit which is connected to digital input RC5 at pin no 24 in portC.

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- S) Crystal oscillator 4Mhz oscillator is connected to the CLKOUT & CLKIN to perform the internal timing requirement. And all inputs that are used are pull down externally while turning on all internal pull ups of the unused inputs to avoid voltage floating
- RB1 and RB2 in portB were used as outputs of the controller . RB1 is assigned to indicator LED and relay which is informed machine controller to keep the machine running once the voltage back to normal is driven by the out put RB2 of portB.

Once the controller is powered digital signal at pin 24(RC5) is checked whether the machine is running. If the machine is in running condition program continues its testing throughout one minute time and turn on LED. Because it needs the stability of the machine. If the condition is correct, it is being checked the machine state to confirm status of running .If the condition is not fulfilled the program will be commenced from the initial start.

Once the above conditions are fulfilled program of the microcontroller checks the voltage of AN0 at the pin2 of portA and ensure it is above or below the reference voltage of AN1 at pin 3 (3.9VDC). If the result of the competition is positive, '0' bit of the status register is set as "one "because no borrow bit is required. If not it is set as "zero". So that output RB1 at pin 34 is set as digital out 1 or 0 by the program.

Once the digital out put appears at RB1 pin numbers, 10,11,12 pins of the machine controller in fig 4.4 which are relevant to the Start, Tip and Stop switches of the machine are connected through the DPDT relay and de-energize after 3 seconds.

The meaning of connecting above points resembles starting the machine at the beginning. When the machine is started, Start and Tip switches are simultaneously kept in the holding stage. This action is done by microcontroller by connecting above three points. The machine controller holds this through the relay volt free contact and releases it after 3 seconds because stored energy in the tensioned yarn beams release their energy to relax the yarns which are between beams and machine as explained in chapter 2 section 2.3.1.

4.5 Schematic circuit diagram

(a) Control circuit for the microcontroller base SPVDA(b)Power circuit for the AC/DC converter and microcontroller

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Figure 4.4 - Control circuit for the microcontroller



In order to provide DC power supply to the micro controller and fast AC to DC converter separate 5V and 9V power supply were used. AC step down center tapped transformer with full bridge rectification, smoothing capacitors and high frequency filtering capacitors were used for each DC supply. Since the output DC voltage levels have to be constant LM 7805, LM7809 and LM7909 regulators were used in 5V,9V and -9V supply circuit respectively as shown the figure 4.5. In addition to the above regulators two 9VDC rechargeable batteries were used to supply power to the circuit during the voltage interruptions.

4.5.1 Some photographs of the implemented Short Period Voltage Dip Actuator



Figure 4.6 - External appearance of the designed microcontroller bases circuit



Figure 4.7 - designed microcontroller bases circuit in the machine control unit



4.5.2 Machine controller circuit diagram



Figure 4.8 -Weaving loom main control unit circuit diagram

Statistical analysis of data

5.1 Category of waste

Data As described in the chapter1 there are two categories of waste which are controllable and uncontrollable waste. Since the solid waste contributing major portion of waste generated in the process, it is very important to analyze the information of solid waste in order to make decision in the company. The waste figure of the weaving department can be shown as below.

Solid waste analysis in year 2008 in kg

		2008										
	Jan	Feb	Mar	Apr	Мау	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Controllable												
Yarn waste	533	578	430	281	554	407	818	638	652	767	521	620
Quality Improvement	847	709	863	514	882 versi	789 V Of	1325	1045 1045	1292	1100	938 11 K a	950
Beam Gating	121	88	70	60	41	80	86	110	115	89	95	88
Alteration	332	231	245	115	332	188	385	275	441	348	318	352
Ware House	291	169	218	55	211	301	288	254	189	193	222	198
Uncontrollable												
Bad Raw Material	13	25	29	65	54	39	48	53	92	32	27	39
Power cut	425	300	295	198	395	388	422	401	375	359	425	482
Maintenance	502	535	381	346	650	743	463	369	379	411	266	295
Mini Bulk	200	205	325	179	255	195	184	204	232	245	211	182
Total	3264	2840	2856	1813	3374	3130	4019	3349	3767	3544	3023	3206

Table 5.1 - Solid waste data in year 2008

Percentage waste of different categories in year 2008



Figure 5.1 – Waste Analysis

5.2 Monitoring of results

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09 09.2009 11.10 pm X X 10.09.2009 7.40 am X X 10.09.2009 2.00 pm X X 11.09.2009 8.00 am X X	07.09.2009	8.00 pm	Х		X	
10.09.2009 7.40 am X X 10.09.2009 2.00 pm X X 11.09.2009 8.00 am X X	09.09.2009	11.10 pm	Х		X	
10.09.2009 2.00 pm X X 11.09.2009 8.00 am X X	10.09.2009	7.40 am	Х		X	
11.09.2009 8.00 am X X	10.09.2009	2.00 pm	Х		X	
	11.09.2009	8.00 am		X		X

Table 5.2-Power failure analysis report

The model unit in figure 4.6 microcontroller base Short Period Voltage Dip Actuator was installed to the weaving machine and monitored and recorded the results during the period from 12th Aug 2009 to 11th Sept 2009. The results were tabulated as per the above table 5.2.

Reference to the table 5.2 approximately out of 30 voltage failures 16 can be managed to run the loom within a period of one month. It is approximately 50% of total waste due to voltage failures. Therefore referring the table 5.2 and figure 5.1 percentage of waste due to voltage dip is approximately 6% of the overall waste. Therefore approximately 2234 kg of mixed product can be saved by installing this controller.

5.3 Analysis of time waste

There are two kinds of machines, these are single and double deck. Each single deck machine includes 10 weaving heads and 20 for the double deck machines. The most significant part of the voltage failure is removing damages and reconnecting tapes (Tagging). In average time taking for the whole process per single tape would be 5second.

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(a) Single deck100 machines www.lib.mr

Tagging time		-	5 sec/tape
Tagging time for 100 looms		-	100x10x5 sec
Average voltage failures per month	t<3sec	-	20 nos
Therefore total loss time		-	20x100x10x5 sec
		-	27 hrs/month

(b) Double deck 20 machines

Tagging time		-	5 sec/tape
Tagging time foe 20 looms		-	20x20x5 sec
Average voltage failures per month	t<3sec	-	20 nos
Therefore total loss time		-	20x20x20x5 sec
		_	11 hrs/month

Therefore total loss time per year due to voltage dips less than 3 sec is approximately 456 hours .This is equivalent to Rs 1.9 million per month due to total capacity of 0.4 million meters per day production. So that annual time loss is approximately equivalent to Rs 23.2 million.

5.4 Analysis of production waste

According to the table 1 Overall mixed production waste in all categories = 38185kg Overall mixed production waste due to voltage failures = 4465kg Overall waste percentage due to voltage failures = 12% = 6% After installing SPPDA waste percentage Therefore equivalent waste due to voltage dips approximately = 2232 kg/year = Rs2.4 million This is equivalent approximately per year So that overall estimated annual saving after installing SPPDA =Rs 25.6million

5.5 Budgetary Requirement Loctropic Theses & Dissertations

Budgetary Requirement Electronic Theses & Dissertations

One of the objectives on this project is to design an economical device to minimize production waste due to voltage failures less than 3sec. The estimated cost for the whole project is as follows

Cost for the components	= Rs3000
Cost for the printed board	== Rs 800
Cost of assembly	= Rs 500
Total cost per unit	= Rs 3300
Estimated cost for 120 units	= Rs 516,000

Total Estimated cost is approximately 2% of the annual saving

Pay back period would be approximately = 8 days By considering this SPVDA will be installed for the weaving machines in the weaving

department, it will be saved at least Rs 25 million.

<u>~</u>~~

Experimental Results and Conclusion

6.1 Testing at site

The new controller was temporally set up at site and a power analyzer model Fluke 1735 was used to take the normal current and voltage Vs time readings during short period interruptions. The machine was given the starting signal and was allowed to run as of normal operation after setting up the new controller and power analyzer .The testing was done for three successive interruptions. The motor current before & after the voltage interruptions were recorded under the short period interruptions as shown in Figure 6.1.



Figure 6.1-Motor Current Variation for momentary interruptions

As the supply voltage to the induction motor decreases the motor speed decrease. Depending on the size and the duration of the voltage dip. the motor speed may recover to its normal value as the voltage amplitude recovers. If the voltage dip magnitude and or duration exceed certain limits the motor would be taken out of the system by the machine controller or protection [6].

In this case if the dip or short period interruption is less than 3sec the motor would be taken out from the machine and consequence restarting must be done. As shown in the Fig. 6.1 during and after the interruption current rises to 2.5 to 3.7 times its normal value during the time less than 3 seconds. Under this scenario the current does not reach higher values for long enough time to trigger any of the motor's protection systems [6]. Fig 6.1 shows that machine operation was not effected by the momentary or voltage dips within time 3 second.

6.2 Conclusion

In this thesis it has been proposed a new approach for reducing waste through automation. The core innovation was triggered to reduce an excessive waste generation due to voltage variations or short period interruptions. It has been used micro controller and other related components to perform this task.

This device can be applied to any application that needs to operate safely during predefine time and voltage levels. The practical results obtained from the application shows that it has no effect to the motor and have a benefit to the organization.

The device was built & integrated with the machine controller to demonstrate the concept. The system was built up with very few pre-made components in an attempt to better understand the technology limits, cost and conditions of building the controller. In doing so it has been noticed the difficulties of the system operation with the number of features and components in the polluted power environment. Therefore the probability of the system working correctly, being the product of all its parts probabilities of working properly.

The new device was built considering all the possible power pollution causes that could be effected to proper operation of the device and mitigation actions were taken during the design stage and while testing. The developed micro controlled base controlled can be set to operate at different time spans. The controller timing was set at 3 seconds maximum for the weaving looms. According to the results collected during one month period approximately 50% of voltage problems can be categorized as short period interruptions or voltage dips. Therefore production waste due to this reason could be recovered by doing small modification at low cost.

According to the Fig 5.1 in cheaper 5 waste due to the voltage problems was 12%. The results were based on average waste figures taken during a period of one year. After installing this new controller, It could be reduced approximately up to 6%. It is equivalent to 2232 kg per year of product saving and 456 hours per year of loss time saving. In terms of financial terms annual saving would be approximately Rs 23.4 million.

Another advantage is rejection of the batches due to high number of joints could be minimized and as a result of customer complains and reprocessing will be reduced.



University of Moratuwa, Sri Lanka. Electronic Theses & Dissertations www.lib.mrt.ac.lk

References:

- [1] Programming the PIC microcontroller with MBasic-Chapter 4.
- [2] Website, <u>http://www.microcgip.com/pic16f87xa</u> datasheet.
- [3] National Operational Amplifiers data book Section 1.
- [4] http://www.lldatasheet.com/datasheet-pdf/30084/TOSHIBA/C1815.html.
- [5] PIC micro Mid-Range MCU Family Reference Manual
- [6] M.Teresa Correia de Barros, Andria Leiria "Journal of Induction Motor Response to Voltage Dips", International Conference on Power Systems Transients-IPST 2003 in New Orleans, USA.
- [7] Juan C. Gomez, "Behavior of Induction motor due to voltage sag and short interruptions" IEEE Transactions on power delivery, Vol. 17, no 2, April 2002
- [8] Magazine of Engineering & Technology-IET.
- [9] Website, http://www.vishay.com/docs/83741/83741.pdf
- [10] Website, http://www.kpsec.freeuk.com/trancirc.htm tuwa, Sri Lanka.

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Appendix - A

ASSEMBLY CODES OF THE PROGRAM

Program	Short Period Voltage Dip Actuator
Microcontroller	PIC 16F877A
Crystal Frequency	4 MHz
Author	H.K.L Gamini

" This part of the program includes defining registers "

porta	equ	0x05	;Register definition using "equ" directive
portb	equ	0x06	
porte	equ	0x07	
trisa	equ	0x85	
trisb	equ	Unive _{0x86}	of Moratuwa, Sri Lanka.
trisc	equ	0x87	rt ac lk
option_reg	equ	0x81	11.a0.1K
adcon0	equ	0x1f	
adconl	equ	0x9f	
dly_count_lsb	equ	0x40	
tlcon	equ	0x10	
time_count_1min	equ	0x26	
pir1	equ	0x0c	
time_count_3s	equ	0x27	
voltage	equ	0x28	
adres_msb	equ	0x1e	
uv_setting	equ	0x23	
status	equ	0x03	
flag_register	equ	0x20	
tmrll	equ	0x0e	
tmr1h	equ	0x0f	

"This part of progra	m includes	defining variables "						
#define	mc_runin	g_flag flag_register,2						
#define	uv_flag	flag_register.3						
"This part of the pro	gram inclue	des macros "						
	INCLUD	INCLUDE "p16f877a.inc"						
	LIST							
bank0	macro	;Selection of bank0						
	bcf	status,5						
	bcf	status,6						
	endm							
bank l	macro	;Selection of bank1						
	bsf	status,5						
	bcf	status,6						
	endm							
start ade	macro	; Start A/D convention						
	bsf	Uniadcon0.2 of Moratuwa, Sri Lanka.						
	endm	Electronic Theses & Dissertations						
off ade	macro	Stop A/D Module						
	bcf	adcon0,0						
	endm							
	org	$0 \mathrm{x} 0 00$;assign the starting address of a program						
	call	sys_init						
start	bef	portb,2						
	bcf	t1con,0						
	clrf	time_count_1min						
	call	mc_state						
	btfss	mc_runing_flag						
	goto	start						
	call	timer1_on						
one min delay	call	mc_state						
	btfss	mc_runing_flag						
	goto	start						
	btfss	pir1.0						
	goto	one_min_delay						

	bef	pir1.0
	incf	time_count_1min,1
	btfss	time_count_1min.6
	goto	one_min_delay
	bcf	tlcon.0
	bsf	portb,2
after 1 min	call	mc_state
	btfss	me_runing_flag
	goto	start
volt_loop	call	read_voltage
	btfss	uv_flag
	goto	runing_volt
	bcf	uv_flag
relay_on	bsf	portb, l
	call	timerl_on
	movlwm	ver0x00 of Moratuwa, Sri Lanka.
	movwfle	ctrotime_count_3s & Dissertations
thr see delay	btfss WW	w.hpir1.0t.ac.lk
	goto	thr_sec_delay
	bcf	pir1,0
	incf	time_count_3s.1
	btfss	time_count_3s.2
	goto	thr_sec_delay
	btfss	time_count_3s,1
	goto	thr_sec_delay
	bcf	t1con,0
	bcf	portb,1
	goto	after_1_min
runing volt	call	mc_state
	btfss	mc_runing_flag
	goto	what_failure
	goto	volt_loop
what failure	call	read_voltage ; check the type of failure
	btfss	uv_flag

	goto	start
	goto	relay_on
read voltage	clrf	voltage
	movlw	b'01000001' ; clock ;channel 0;module on
	movwf	adcon0
	call	read_adc
	movfw	adres_msb
	movwf	voltage
"This part includes s	election of c	lock and AD ON"
read uv setting	movlw	b'01001001' ;clock (FOSC/8) ;ch1.module on
	movwf	adcon0
	call	read_adc
	clrf	uv_setting
	movfw	adres_msb
	movwf	Unuvesetting :save the uv setting Sri Lanka
check_volt	bef	Eluvenagic Theses & Dissertations
	movfw	wvuv setting rt. ac.lk
	subwf	voltage,0
	btfse	status.0 ;Is there a uv
	return	;no
	bsf	uv_flag ;yes
	return	
me state	clrwdt	;Reset watch dog timer
	bcf	me_runing_flag
	btfsc	porte,5
	bsf	mc_runing_flag
	return	
read ade	call	wait : For acquisition delay
	start_ade	;Start A/D conversion
ade loop	btfsc	adcon0,2 :Is end of conversion
	goto	adc_loop
	off_ade	;0ff A/D Module
	return	

"This part includes acquisition delay "

wait	mövlw	0xE7 ;acquisition delay
	movwf	dly count lsb
wait loop	clrwdt	
	incfsz	dly_count_lsb
	goto	wait_loop
	return	
timer1 on	clrf	tmr1h
	clrf	tmrll
	movlw	b'00110101'
	movwf	tlcon
	return	
" This part includes	configuration of	of portb as inputs and outputs "
sys init	bank l	
-	movlw	b'11111001' ;configer portb(input/output)

movwf University of Moratuwa, Sri Lanka.

"This part includes configuration of porta as A/D port" Dissertations

movlwwww.b'00110000'c];configer porta(Λ/D port)/ Λ/D

result format

movwf	adconl	
" This part includes configuration o	of porte as digita	l input "
movlw	6'11111111	configure porte inputs;
movwf	trise	
movlw	b'01010100'	portb pull-up enable;
movwf	option reg	
bank()		
clrf	adres_msb	initialy clear A/D result register;
bcf	adcon0.7	;A/d conversion clock select
bsf	adcon0,6	;A/d conversion clock select
bcf	portb,1	initialy OFF the relay
call	read_uv_sett	ing ;Read under voltage setting
return		
END		

Transistor Datasheet:

TOSHIBA TRANSIS	TOR SILICON	NPN EPITAXI	AL TYPE	(PCT PROCESS)
	250	181	5	
UDIO FREQUENCY GENERAL PURP RIVER STAGE AMPLIFIER APPLICAT	OSE AMPLIFIER FIONS.	APPLICATIO	NS.	Unit in mm
High Voltage and High Current : VĊEO=50V (Min.), IC=11 Excellent hFE Linearity : hFE(2)=100 (Typ.) at VCP : hFE (IC=0.1mA)/hFE (IC Low Noise : NF=1dB (Typ.)	nt 50mA (Max.) E=6V, IC=150 =2mA)=0.95 (') at f=1kHz	ЭmA Тур.)		
Complementary to $2SA1015$ (O	, Y, GR class)			
Complementary to 2SA1015 (O IAXIMUM RATINGS (Ta = 25°C) CHARACTERISTIC	, Y, GR class) SYMBOL	RATING	UNIT	
Complementary to 2SA1015 (O IAXIMUM RATINGS (Ta = 25°C) CHARACTERISTIC Collector-Base Voltage	Y, GR class) SYMBOL	RATING 60	UNIT V	
Complementary to 2SA1015 (O IAXIMUM RATINGS (Ta = 25°C) CHARACTERISTIC Collector-Base Voltage Collector-Emitter Voltage	Y, GR class) SYMBOL VCBO VCEO	RATING 60 50	UNIT V V	
Complementary to 2SA1015 (O IAXIMUM RATINGS (Ta = 25°C) CHARACTERISTIC Collector-Base Voltage Collector Emitter Voltage Emitter-Base Voltage	Y, GR class) SYMBOL VCBO VCEO VEBO	RATING 60 50 5	UNIT V V	
Complementary to 2SA1015 (O IAXIMUM RATINGS (Ta = 25°C) CHARACTERISTIC Collector-Base Voltage Collector-Emitter Voltage Emitter-Base Voltage Collector Current	Y, GR class) SYMBOI, VCBO VCBO VEBO IC	RATING 60 50 5 (150)	UNIT V V MA	
Complementary to 2SA1015 (O IAXIMUM RATINGS (Ta = 25°C) CHARACTERISTIC Collector-Base Voltage Collector Emitter Voltage Emitter-Base Voltage Collector Current Base Current	Y, GR class) SYMBOL VCBO VCBO VEBO IC IB	RATING 60 50 5 150 50 50 50	UNIT V V mA mA	Les 1, Les 1,
Complementary to 2SA1015 (O IAXIMUM RATINGS (Ta = 25°C) CHARACTERISTIC Collector-Base Voltage Collector Emitter Voltage Emitter-Base Voltage Collector Current Base Current Collector Power Dissipation	Y, GR class) SYMBOL VCBO VCEO VEBO IC IB PC	RATING 60 50 5 150 50 400	UNIT V V MA mA mW	JEDEC DI TO-92 TATO
Complementary to 2SA1015 (O MAXIMUM RATINGS (Ta = 25°C) CHARACTERISTIC Collector-Base Voltage Collector Emitter Voltage Emitter-Base Voltage Collector Current Base Current Collector Power Dissipation Junction Temperature	SYMBOL VCBO VCBO VEBO IC IB PC T;	RATING 60 50 5 150 50 400 125	UNIT V V MA mA mW	LEIAJ SC-43 TOSHIBA 2-5F1B

CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Collector Cut off Current	ICBO	$V_{CB} = 60V, I_E = 0$			0.1	μΛ
Emitter Cut-off Current	1 _{EBO}	$V_{EB} = 5V, I_C = 0$			0.1	μA
DC Current Gain	hFE(1) (Note)	$V_{CE} = 6V, I_C = 2mA$	70		700	
	hFE(2)	$V_{CE} = 6V, I_{C} = 150mA$	25	100		
Collector-Emitter Saturation Voltage	V _{CE(sat)}	I_{C} :: 100mA, I_{B} ::: 10mA		0.1	0.25	v
Base Emitter Saturation Voltage	V _{BE(sat)}	$I_C = 100 \text{mA}, I_B = 10 \text{mA}$	l —		1.0	V
Transition Frequency	fŢ	$V_{CE} = 10V, I_{C} = 1mA$	80		ļ	MHz
Collector Ouput Capacitance	Cob	$V_{CB} = 10V, I_E = 0, f = 1MHz$		2.0	3.5	pF
Base Intrinsic Resistance	r _{bb} ,	rbb' $V_{CE} = 10V, I_E = -1m\Lambda$ f = 30MHz		50		Ω
Noise Figure	NF	$V_{CE}=6V, I_{C}=0.1mA$ f=1kHz, R _G =10k Ω		1.0	10	dB
		X 100 040 CH . 000	1. 400	DT	250~5	700

Note : hFE Classification 0 : 70~140 Y : 120~240 GR : 200~400 BL : 350~700

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1997-04-10 1/3

Silicon Rectifier Diode Datasheet :



Working Peak Reverse Voltage DC Blocking Voltage	V _{RWM} VR	50	100	200	400	600	800	1000	V
RMS Reverse Voltage	V _{R(RMS)}	35	70	140	280	420	560	700	V
Average Rectifier Forward Current Per Leg T _C =125 °	1 _{EOAVC}				1.0				Α
Non-Repetitive Peak Surge Current (Surge applied at rate load conditions halfware, single phase, 60Hz)	lesw				30				A
Maximum Instantaneous Forward Voltage (IF =1.0 Amp T _C = 25%)	V.				1.1				V
$\begin{array}{l} \mbox{Maximum Instantaneous Reverse Current} \\ (Rated DC Voltage, T_C = 25\%) \\ (Rated DC Voltage, T_C = 100\%) \end{array}$	I _R				5 D 50				uA
Typical Junction Capacitance (Reverse Voltage of 4 volts & f=1 MHz)	C,				15				рF
Typical Thermal Resistance	R _{e,A}				50				C/W
Operating and Storage Junction Temperature Range	Т. Т. Т.;				65 to +1	75			· · · · · · · · · · · · · · · · · · ·







PTROONT OF RATED REVERSE VOLTAGE (, ,)



NUMBER OF CYCLES AT 60 17

62

PCB Relay Datasheet:

.

OMRON **PCB Relay**

Miniature Relay for Signal Circuits

- Wide switching power of 10 µA to 2 A.
- High dielectric strength coil-contacts:1,000 VAC; open contacts: 750 VAC.
 Conforms to FCC Part 68 requirements.
- Ag + Au clad bifurcated crossbar contacts and fully sealed for high contact reliability.
- New 150-mW relays with high-sensitivity.

Ordering Information

RoHS Compliant Refer to pages 16 to 17 for details.



3, 5, 6, 9, 12, 24, 48 VDC

ł

91 9 FCC

G5V-2

Classification	Contact form	Contact type	Contact material	Enclosure ratings	Mode
Cassincation	Dent	Bifurcated crossbar	Ac + Au-Alloy	Fully sealed	G5V-2
Stanoaro					G5V-2-H1
High-sensitivity		tropic '	DOGO NT	Discontat	COLLC.
Example: G5V-	2 <u>12 VDC</u> Bated co	voltage O. mrt.			
	THE CO O	in tunago			
Model Number Le	gend				
Model Number Le	gend VDC				
Model Number Le G5V - [] _ 1 2 、	gend VDC 3				

Specifications

Coil Ratings

2: DPDT

Standard Models

Bated voltage		3 VDC	5 V0C	6 VDC	9 VDC	12 VDC	24 VDC	48 VDC
Rated current		166.7 mA	100 mA	83.3 mA	55.6 mA	41.7 mA	20.8 mA	12 mA
Coil resistance		18 \Q	50 Ω	72 \	162 \	289 \	1.152 Ω	4,000 Ω
Coil inductance	Armature OFF	0.04	0.09	0.16	0.31	0.47	1.98	7.23
(H) (ref. value)	Armature ON	0.05	0.11	0.19	0.49	0.74	2.63	10.00
Must operate vo	Itage	75% max. c	of rated voltag	је				
Must release vol	tage	5% min. of	rated voltage					
Max, voltage	120% of rated voltage at 23°C							
						Annrox		

Note:
 The rated current and coil resistance are measured at a coil temperature of 23°C with a totarance of ±10%.
 Operating characteristics are measured at a coil temperature of 23°C.
 The maximum voltage is the highest voltage that can be imposed on the relay coil.

H1: High-sensitivity

— OMRON — _____ G5V-2 G5V-2 -

High Sensitivity Models

Date of contracts		1a vinc	LS VDC	6 VDC	: 9 VDC	12 VDC	24 VDC	48 VDC
Rated voltage		5 V 50		25 mA	16.7 mA	12.5 mA	8.33 mA	6.25 mA
Rated current		60.0	166.7.0	240 12	540 \Q	960 12	2.880 \	7,680 Ω
Coil inductance	Armature ON	0.18	0.46	0.70	1.67	2.90	6.72	20.1
(H) (ref. value)	Armature OFF	0.57	0.71	0.97	2.33	3.99	9.27	26.7
Must operate vol	tage	75% max.	of rated voltag	e				
Must release vol	lage	5% min o	r rateo voltage					
Max. voltage		180% of rated voltage at 23 C						voltage at 23 °C
Power consumption Approx. 150 mW						Approx. 200 mW	Approx. 300 mW	

Note: 1. The rated current and coil resistance are measured at a coil temperature of 23 °C with a tolerance of ±10%.
 Operating characteristics are measured at a coil temperature of 23 °C.
 The maximum voltage is the highest voltage that can be imposed on the relay coil.

Contact Ratings

ltem	Standard models	High sensitivity models
Load	Resistive leac (cosp - 1)	
Rated load	0.5 A at 125 VAC: 2 A at 30 VDC	0.5 A at 125 VAC: 1 A at 24 VDC
Contact material	Ag + Au-clad	
Rated carry current	2 A	
Max, switching voltage	125 VAC. 125 VDC	
Max. switching current	2 A	1 A
Max. switching power	62.5 VA, 60 W	62.5 VA. 24 W
Failure rate (reference value) (See note.)	0.01 mA at 10 mVDC	

Note: P level: λ₀₀ = 0.1 x 10⁻⁶/operation This value was measured a: a switching frequency of 120 operations/min and the criterion of contact resistance is 50 Ω. This value may vary depending on the switching frequency and operating environment. Atways double-check relay suitability uncer actual operating conditions

Item	Standard models	High sensitivity models
Contact resistance (See note 1.)	50 m ⁽² max	100 mΩ max.
Operate time	7 ms.max.ectrollic 1 mes	es & Dissertations
Release time	3 ms max.	
Max. operating frequency	Mechanical, 36:000 operations/hr Electrical: 1,800 operations/hr (uncer rated load)	
Insulation resistance (See note 2.)	1,000 MΩ min. (at 500 VDC)	
Dielectric strength	1.000 VAC, 50/60 Hz for 1 min between coil and contacts 1.000 VAC, 50/60 Hz for 1 min between con- tacts of different polarity 750 VAC, 50/60 Hz for 1 min between contacts of same polarity	1,000 VAC, 50:60 Hz for 1 min between coll land contacts 1,000 VAC, 50:60 Hz for 1 min between con- lacts of different polarity 500 VAC, 50:60 Hz for 1 min between contacts of same polarity
Impulse withstand voltage	1,500 V (10 x 160 µs) between coil and contacts (conforms to FCC Part 68)	
Vibration resistance	Destruction: 10 to 55 to 10 Hz, 0.75-mm single amplitude (1.5-mm double amplitude) Malfunction: 10 to 55 to 10 Hz, 0.75-mm single amplitude (1.5-mm double amplitude)	
Shock resistance	Destruction 1,000 m/s ² (approx. 100G) Mal ² unction: 200 m/s ² (approx. 20G)	Destruction: 1,000 m/s ² (approx. 100G) Malfunction. 100 m/s ² (approx. 10G)
Endurance	Mechanical: 15,000.000 operations min. (a: 36,000 operations/hr) Electrical: 100,000 operations min. (at 1,900 operations/hr)	
Ambient temperature	Operating:25° C to 65° C (with no icing)	Operating: -25 °C to 70 °C (with no rong)
Ambient humidity	Operating: 5% to 85%	
Weight	Approx. 5 g	

Note: The above values are initial values.

Note: The down vinces as many vinces.
 Note: 1. The contact resistance was measured with 10 mA at 1 VDC with a voltage drop method.
 2. The insulation resistance was measured with a 500-VDC megohimmeter applied to the same parts as those used for checking the dielectric strength.
G5V-2

OMRON

Approved Standards

UL478, UL1950, UL508 (File No. E41515)/CSA C22.2 No.0, No.14 (File No. LR31928)

l	Contact form	Coil ratings	G5V-2	Contact ratings G5V-2-H1
	UPDT	3 to 48 VDC	0.6 A, 125 VAC (general use) 0.6 A, 110 VDC (resistive load) 2 A, 30 VDC (resistive load)	0.5 A, 125 VAC (general use) 0.2 A, 110 VDC (resistive load) 1 A, 24 VDC (resistive load)

Engineering Data



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G5V-2

Contactor Relay Threshold voltages:



Sector and competitive descent and competitive descent and the sector of
December 1994

Operational Amplifier Datasheet :

National Semiconductor

LM101A/LM201A/LM301A Operational Amplifiers

General Description

The LM101A series are general purpose operational amplifiers which feature improved performance over industry standards like the LM709. Advanced processing techniques make possible an order of magnitude reduction in input currents, and a redesign of the biasing circuitry reduces the temperature drift of input current. Improved specifications include:

- Offset voltage 3 mV maximum over
- temperature (LM101A/LM201A)
- Input current 100 nA maximum over temperature (LM101A/LM201A)
- Offset current 20 nA maximum over temperature (LM101A/LM201A)
- Guaranteed drift characteristics
- Offsets guaranteed over entire common mode and supply voltage ranges
- Slew rate of 10V/µs as a summing amplifier

This amplifier offers many features which make its application nearly foolproof: overload protection on the input and output, no latch-up when the common mode range is exceeded, and freedom from oscillations and compensation with a single 30 pF capacitor. It has advantages over internally compensated amplifiers in that the frequency compensation can be tailored to the particular application. For example, in low frequency circuits it can be overcompensated for increased stability margin. Or the compensation can be optimized to give more than a factor of ten improvement in high frequency performance for most applications.

In addition, the device provides better accuracy and lower noise in high impedance circuitry. The low input currents also make it particularly well suited for long interval integrators or timers, sample and hold circuits and low frequency waveform generators. Further, replacing circuits where matched transistor pairs buffer the inputs of conventional IC op amps, it can give lower offset voltage and a drift at a lower cost.

The LM101A is guaranteed over a temperature range of -55°C to +125°C, the LM201A from -25°C to +85°C, and the LM301A from 0°C to +70°C.



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bsolute Maximum Ratings Military/Aerospace specified devices are re	quired, please contact the National S	Semiconductor Sales Offic
	LM101A/LM201A	LM301A
Supply Voltage	± 22V	+ 18V
Differential Input Voltade	+ 30V	+ 30V
Unierential impart Voltage	+15V	+ 15V
Output Short Circuit Duration (Note 2)	Continuous	Continuous
Operating Ambient Temp. Range	 - 55°C to +125°C (LM101A) - 25°C to +85°C (LM201A) 	0°C to → 70°C
T _J Max		100°C
H-Package	150°C	100°C
N-Package	150-0	100 0
J-Package	150°C	100 0
Power Dissipation at $T_A = 25^{\circ}C$	500 M	200 mW
H-Package (Still Air)	500 mW	300 HIVV
(400 LF/Min Air Flow)	1200 mW	700 mvv
N-Package	900 mW	500 mW
J-Package	1000 mW	650 mw
Thermal Resistance (Typical) $ heta_{iA}$		10000
H-Package (Still Air)	165°C/W	165°C/W
(400 LF/Min Air Flow)	67°C/W	67°C/W
N Package	135°C/W	135°C/W
J-Package	110°C/W	110°CmW
(Typical) θ_{iG}		0520 (14)
H-Package	25°C/W	25°C/W
Storage Temperature Range	65°C to + 150°C	- 65°C to + 150°C
Lead Temperature (Soldering, 10 sec.)		
Metal Can or Ceramic	300°C	300°C
Plastic	260°C	260°C
ESD Tolerance (Note 5)	2000V	2000V

Electrical Characteristics (Note 3) $T_A = T_J$

ParameterConditionInput Offset Voltage $T_A = 25^{\circ}C$, $R_S = 50$ kgInput Offset Current $T_A = 25^{\circ}C$ Input Bias Current $T_A = 25^{\circ}C$ Input Resistance $T_A = 25^{\circ}C$ Supply Current $T_A = 25^{\circ}C$ Large Signal Voltage Gain $T_A = 25^{\circ}C$, $V_S = \pm 15$ Vour = $\pm 10V$, $R_L \ge 3$ Least Offset Voltage $R_B = 50$ kQ	$\frac{V_{S} = \pm 20}{V_{S} = \pm 15}$	Min SC 1.5 7 50	Typ 0.7 1.5 30 4.0 1.8	Max 2.0 10 75 3.0	Min 0.5	Typ 2.0 3.0 3.0 70 2.0 1.8 1.8	Max 7.5 50 250	mV nA nA MΩ mA
Input Offset Voltage $T_A = 25^{\circ}C, R_S \pm 50 \text{ km}$ Input Offset Current $T_A = 25^{\circ}C$ Input Bias Current $T_A = 25^{\circ}C$ Input Resistance $T_A = 25^{\circ}C$ Supply Current $T_A = 25^{\circ}C$ Large Signal Voltage Gain $T_A = 25^{\circ}C, V_S = \pm 15$ Vour = $\pm 10V, R_L \ge 3$	$\frac{V_{S} - \pm 20}{V_{S} - \pm 15}$	1.5 1.5 1.5	0.7 1.5 30 4.0 1.8	2.0 10 75 3.0	0.5	2.0 11 3.0 70 2.0 1.8	7.5	mV nA nA MΩ mA
Input Offset Current $T_A = 25^{\circ}C$ Input Bias Current $T_A = 25^{\circ}C$ Input Resistance $T_A = 25^{\circ}C$ Supply Current $T_A = 25^{\circ}C$ Large Signal Voltage Gain $T_A = 25^{\circ}C, V_S = \pm 15$ Vour = $\pm 10V, R_L \ge 2$ Least Offset Voltage $R_B = 50 k\Omega$	$\frac{V_{S} = \pm 20}{V_{S} - \pm 15}$	SC 1.5 / 50	30 4.0 1.8	10 75 3.0	0.5	2.0 2.0 1.8	50 250 3.0	nA nA MΩ mA
Input Bias Current $T_A = 25^{\circ}C$ Input Resistance $T_A = 25^{\circ}C$ Supply Current $T_A = 25^{\circ}C$ Large Signal Voltage Gain $T_A = 25^{\circ}C, V_S = \pm 15$ Vour = ± 10V, RL ≥ 2 Least Official Voltage $R_B = 50 k\Omega$	$\frac{ V_{S} = \pm 20\rangle}{ V_{S} - \pm 15\rangle}$	1.5 / / 50	<u>30</u> <u>4.0</u> <u>1.8</u>	75 3.0	0.5	70 2.0 1.8	250	nA MΩ mA
Input Resistance $T_A = 25^{\circ}C$ Supply Current $T_A = 25^{\circ}C$ Large Signal Voltage Gain $T_A = 25^{\circ}C, V_S = \pm 15$ Vour = $\pm 10V, R_L \ge 2$ Least Official Voltage $R_D = 50 k\Omega$	$V_{\rm S} = \pm 20$ $V_{\rm S} = \pm 15$ $V_{\rm S} = \pm 15$	1.5 / 50	4.0	3.0	0.5	2.0	3.0	MΩ mA
Supply Current $T_A = 25^{\circ}C$ Large Signal Voltage Gain $T_A = 25^{\circ}C, V_S = \pm 15$ $V_{OUT} = \pm 10V, R_L \ge 2$ Least Official Voltage $R_{D} = 50 kQ$	$\frac{V_{\rm S} = \pm 20}{V_{\rm S} - \pm 15}$	50	1.8	3.0		1.8	3.0	mA
Large Signal Voltage Gain $T_A = 25^{\circ}C, V_S = \pm 15$ $V_{OUT} = \pm 10V, R_L \ge 5$ Vector Official Voltage	$V_{\rm S} = \pm 15$ SV 2 kΩ	50				1.8	3.0	m۵
Large Signal Voltage Gain $T_A = 25^{\circ}C, V_S = \pm 15$ $V_{OUT} = \pm 10V, R_L \ge 2$ Least Official Voltage $R_B = 50 \text{ k}\Omega$	5V 2 kΩ	50						111/2
Ba 50 k()			160		25	160		V∕mV
input Onset voltage				3.0			10	mV
Average Temperature Coefficient $R_S = 50 \text{ k}\Omega$ of Input Offset Voltage			3.0	15		6.0	30	μV/°C
Input Offset Current				20			70	nA
Average Temperature Coefficient 25°C TA TMAX	$\begin{array}{l} 25^{\circ}\text{C} \leftarrow \text{T}_{\text{A}} \leftarrow \text{T}_{\text{MAX}} \\ \text{T}_{\text{MIN}} \doteq \text{T}_{\text{A}} \leq 25^{\circ}\text{C} \end{array}$		0.01	0.1		0.01	0.3	nA/°C
of Input Offset Current $T_{MIN} \cong T_A \le 25^{\circ}C$			0.02	0.2		0.02	0.6	nA/°C

				LM101A/LM201A			LM301A			Units
Parameter		Conditions		Min	Тур	Мах	Min	Тур	Max	
put Bias Current						0.1			0.3	μA
upply Current	TA - TMAX. Ve	3 + 20V			1.2	2.5				mA
arge Signal Voltage Gain	V _S — ±15V. V _{OUT} — ±10V R _L = 2k			25			15			V/m
utput Voltage Swing	$V_{\rm S} = \pm 15 V$		$R_L \approx 10 \; k\Omega$	+ 12	±14		±12	± 14		V
			$R_L = 2 k\Omega$	±10	+ 13		110	± 13		V
put Voltage Range	V _S - +20V			+ 15						V
	$V_{\rm S} = \pm 15 V$				+ 15, - 13		+ 12	+ 15, - 13		V
ommon-Mode Rejection Ratio	$R_S \le 50 \ k\Omega$			80	96		70	90		dE
upply Voltage Rejection Ratio	Rs _ 50 kf1			80	96		70	96		dE
Input Voltage	Range Un	20 ULT District Contract of C	Swing www.ex- .uk .uk .uk .uk .uk .uk .uk .uk	0112 125°C 2	100 00 100 100 100 100 100 100	Voltaç	10 SUPPLY V	anka. brs 5°C ≤ T _A ≤ 125°C 15 0LTAGE (±V)	20 TL/H	(7752 -
Guaranteed Perfe	ormance (Characte	ristics LM	1301A						
Input Voltage	2 Range			70°C	100 94 199 199 199 199 199 199 199 199 199	volta	ge Gail	n NINUM 0°T ≤ T _A ≤70°C		

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Optocoupler CNY17-1 Datasheet:

+optor

Global Supplier of Optoelectronic Solutions ALL Product Lead Free, RoHs Compliant

Features:

1. Current transfer ratio

(CTR 40-80% at IF=10mA Voe=5V)

(Viso = 5300Vims, 7500Vpk).

2. High isolation voltage between input and output

CNY17-1

Schematic:



For dimensions and pin-outs, see the last page of this document.

Orderina:

Suffix to Standard Part Number

- V = VDE Compliant
- G = 10mm Lead Spread
 - S = Surface Mount Lead-form
 - T = Tape & Reel

University of Moratuwa, Sri Lanka

Absolute Maximum Ratings: Parameter Symbol Rating Unit Peak forward current FLL 1 Α VR Reverse voltage Input PD 70 mΨ Power dissipation Collector-emitter voltage VOB 70 V VECO 6 V Emitter-collector voltage Voac 60 V Collector-base voltage Lmitter-base voltage VFBC 6 V Output Collector current k 50 mΑ Collector power dissipation Pd 150 m₩ Total power dissipation Ptot 200 m₩ Isolation voltage 1 minute Viso 5300 Vrms Viso 7500 Vpk -55 to +100 Operating temperature Topr Storage temperature Tstg -55 to +125 Soldering Temperature 10 seconds Lsol 260

Electrical Characteristics:

	Parameter	Symbol	Conditions	MN	TYP.	MAX	Unit	
	Forward voltage	VF.	IF=20mA	-	1.2	1.4	V	
	Peak forward voltage	VEM	IFM=0.5A	-	-	3.5	V	
Input	Reverse current	R	VR=4V			10	ιA	
	Terminal capacitance	Ct	V=0, f=1kH2	-	30		рF	
Output	Callector dark current	040	VOE=20V		-	0.1	цА	
	Current transfer ratio	Cik	IF=10mA, VCE=5V	4()		80	%	
Г	Collector-emitter saturation voltage	VCR(sat)	IF=10mA, Ic=2.5mA		0.1	0.4	V	
Tranfer	Isolation resistance	Riso	DC500V	5x10 ¹⁰	10 11		ohm	
charac	Floating capacitance	Cf	V=Q, I=11/0HZ		0.6	10	Pí	
teristics	Cat-off frequency	ť	Vcc=5V.lc=2mA.RL=100ohm		80		kH7	
	Response time (Rsc)	tr	Vce=2V,lc=2mA,RL=100ohm	-	5	20	us	
	Response time (Fall)	1 11			.1	20		

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Superior OPTO Part Number:





Current Transfer Ratio Fig. 1 Vs. Forward Current









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Photo graphs of the machine in production:



